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Docket No. 1422-0611P
Applic. Serial No. 10/727,571

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A polishing composition for memory hard disk comprising water having a pH of from 1 to 4.5 and an abrasive consisting essentially of silica particles, wherein the silica particles have a particle size distribution wherein silica particles having a size less than 40 nm are present in said composition, and in which a relationship of a particle size (R) in nm at a range of from 40 to 45 nm and a cumulative volume frequency % (V) in a graph of particle size-cumulative volume frequency obtained by plotting a cumulative volume frequency (%) of the silica particles counted from a small particle size side satisfy the relationship where the cumulative volume frequency (V) in % is determined to be equal to or greater than the sum of the particle size (R) in nm plus and 50,

wherein the silica particles have a particle size distribution wherein silica particles having a size of from 10 to less than 40 nm are present in said composition, and

wherein the particle size is determined by observation with a transmission electron microscope (TEM).

2. (Original) The polishing composition according to claim 1, wherein the silica particles are colloidal silica particles.

3. (Original) The polishing composition according to claim 1, further comprising at least one member selected from the group consisting of acids, salts thereof and oxidizing agents.

4. (Original) The polishing composition according to claim 2, further comprising at least one member selected from the group consisting of acids, salts thereof and oxidizing agents.

5. (Canceled) ~~The polishing composition according to claim 1, wherein pH is from 1 to 4.5.~~

6. (Original) The polishing composition according to claim 2, wherein pH is from 1 to 4.5.

7. (Original) The polishing composition according to claim 3, wherein pH is from 1 to 4.5.

8. (Original) The polishing composition according to claim 4, wherein pH is from 1 to 4.5.

9. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 1.

10. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 2.

11. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 3.

12. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 4.

13. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 5.

14. (Withdrawn) A process for reducing surface roughness (TMS-Ra) of a substrate for memory hard disk comprising the step of polishing a substrate for memory hard disk with the polishing composition of claim 6.

15. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 1.

16. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 2.

17. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 3.

18. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 4.

19. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 5.

20. (Withdrawn) A method for manufacturing an Ni-P plated substrate for memory hard disk, comprising the step of polishing an Ni-P plated substrate for memory hard disk with the polishing composition of claim 6.

21. (Cancelled)